

# TEMIC

Siliconix

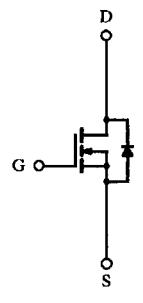
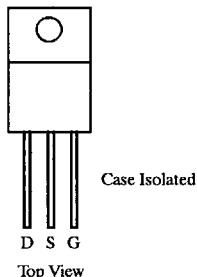
**2N7075**

## N-Channel Enhancement-Mode Transistor

### Product Summary

V <sub>DS</sub> (V)	r <sub>D(on)</sub> (Ω)	I <sub>D</sub> (A)
100	0.065	30

TO-254AA  
Hermetic Package



### Absolute Maximum Ratings (T<sub>C</sub> = 25°C Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	
Continuous Drain Current (T <sub>J</sub> = 150°C)	I <sub>D</sub>	30	A
T <sub>C</sub> = 100°C		24	
Pulsed Drain Current	I <sub>DM</sub>	120	W
Maximum Power Dissipation	P <sub>D</sub>	150	
T <sub>C</sub> = 100°C		60	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C
Lead Temperature (1/16" from case for 10 sec.)	T <sub>L</sub>	300	

6

N/P-Channel  
MOSFETs

### Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	R <sub>thJA</sub>	50	0.83	°C/W
Maximum Junction-to-Case	R <sub>thJC</sub>			
Case-to-Sink	R <sub>thCS</sub>	0.2		

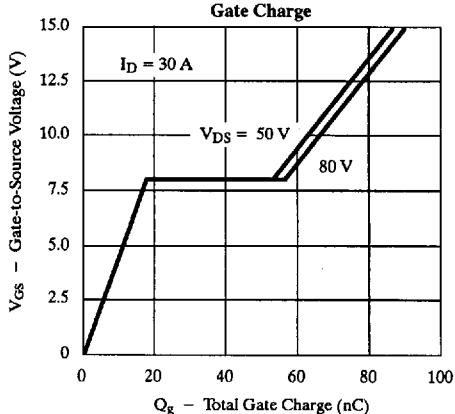
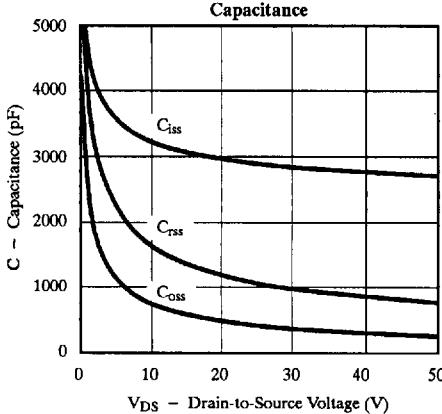
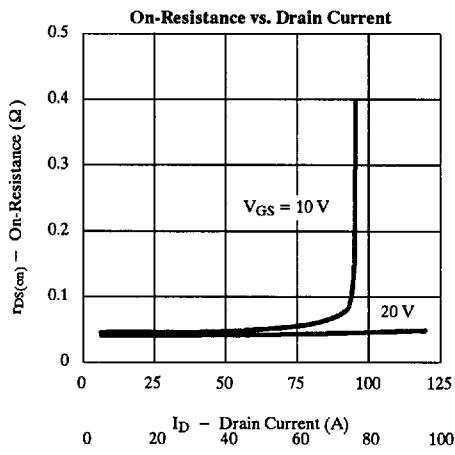
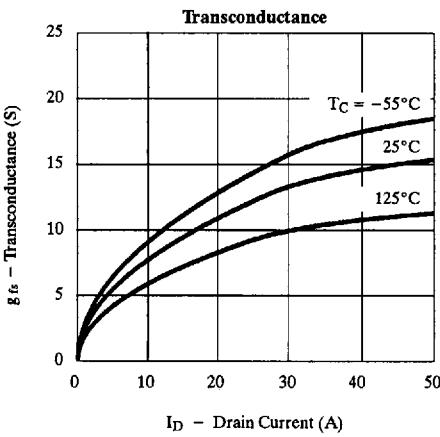
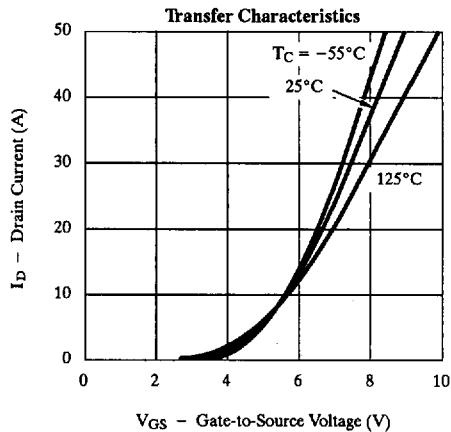
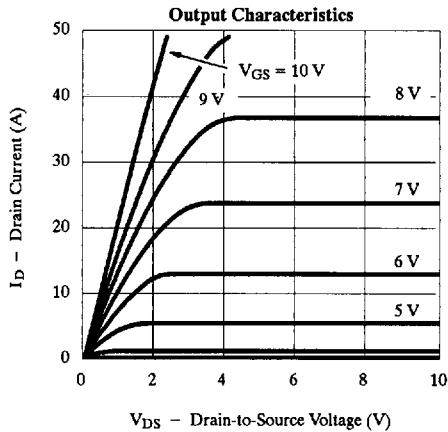
Specifications ( $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

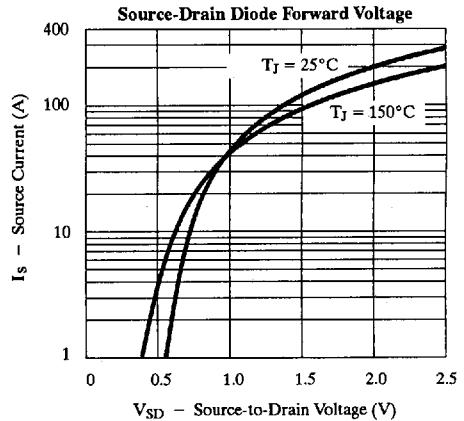
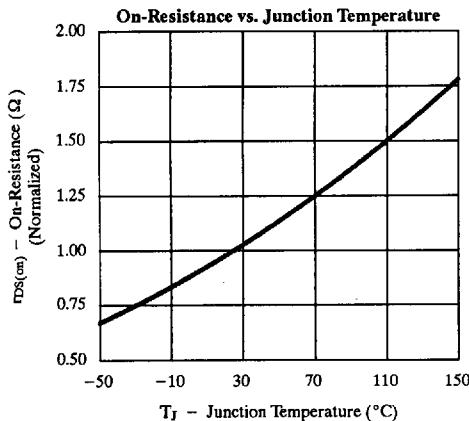
Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ <sup>a</sup>	Max	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2.0		4.0	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$			25	
		$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125^\circ\text{C}$			250	$\mu\text{A}$
On-State Drain Current <sup>b</sup>	$I_{D(\text{on})}$	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			A
Drain-Source On-State Resistance <sup>b</sup>	$r_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}, I_D = 24 \text{ A}$		0.053	0.065	
		$V_{GS} = 10 \text{ V}, I_D = 24 \text{ A}, T_J = 125^\circ\text{C}$		0.08	0.10	$\Omega$
Forward Transconductance <sup>b</sup>	$g_f$	$V_{DS} = 15 \text{ V}, I_D = 24 \text{ A}$	9	11	27	S
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		2800		
Output Capacitance	$C_{oss}$			1100		
Reverse Transfer Capacitance	$C_{rss}$			400		pF
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$		62	125	
Gate-Source Charge <sup>c</sup>	$Q_{gs}$			17	22	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			35	65	nC
Turn-On Delay Time <sup>c</sup>	$t_{d(on)}$			15	35	
Rise Time <sup>c</sup>	$t_r$	$V_{DD} = 50 \text{ V}, R_L = 1.67 \Omega$ $I_D \approx 30 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 2.4 \Omega$		80	150	
Turn-Off Delay Time <sup>c</sup>	$t_{d(off)}$			60	125	ns
Fall Time <sup>c</sup>	$t_f$			50	100	
<b>Source-Drain Diode Ratings and Characteristics</b>						
Continuous Current	$I_S$				30	
Pulsed Current	$I_{SM}$				120	A
Diode Forward Voltage <sup>b</sup>	$V_{SD}$	$I_F = 30 \text{ A}, V_{GS} = 0 \text{ V}$	0.6		1.9	V
Reverse Recovery Time	$t_{rr}$	$I_F = 30 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		180	400	ns
Reverse Recovery Charge	$Q_{rr}$			0.6		$\mu\text{C}$

## Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .
- c. Independent of operating temperature.

## Typical Characteristics (25°C Unless Otherwise Noted)



**2N7075****Typical Characteristics (25°C Unless Otherwise Noted)****Thermal Ratings**